

October 2014

MOC205M, MOC206M, MOC207M, MOC211M, MOC212M, MOC213M, MOC216M, MOC217M 8-pin SOIC Single-Channel Phototransistor Output Optocoupler

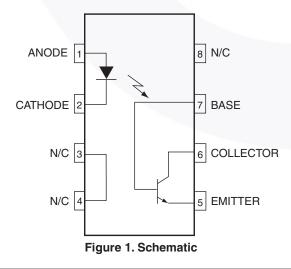
Features

- Closely Matched Current Transfer Ratios
- Minimum BV_{CEO} of 70 V Guaranteed
 MOC205M, MOC206M, MOC207M
- Minimum BV_{CFO} of 30 V Guaranteed
 - MOC211M, MOC212M, MOC213M, MOC216M, MOC217M
- Low LED Input Current Required for Easier Logic Interfacing
 - MOC216M, MOC217M
- Convenient Plastic SOIC-8 Surface Mountable Package Style, with 0.050" Lead Spacing
- Safety and Regulatory Approvals:
 - UL1577, 2,500 VAC_{RMS} for 1 Minute
 - DIN-EN/IEC60747-5-5, 565 V Peak Working Insulation Voltage

Applications

- Feedback Control Circuits
- Interfacing and Coupling Systems of Different Potentials and Impedances
- General Purpose Switching Circuits
- Monitor and Detection Circuits

Schematic



Description

These devices consist of a gallium arsenide infrared emitting diode optically coupled to a monolithic silicon phototransistor detector, in a surface mountable, small outline, plastic package. They are ideally suited for high-density applications, and eliminate the need for through-the-board mounting.

Package Outline

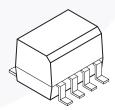


Figure 2. Package Outline

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Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Parameter | | Characteristics |
|--|------------------------------------|-----------------|
| Installation Classifications per DIN VDE | per DIN VDE < 150 V _{RMS} | |
| 0110/1.89 Table 1, For Rated Mains Voltage | < 300 V _{RMS} | I–III |
| Climatic Classification | | 55/100/21 |
| Pollution Degree (DIN VDE 0110/1.89) | | 2 |
| Comparative Tracking Index | | 175 |

| Symbol | Parameter | Value | Unit | |
|----------------------|---|--------------------|-------------------|--|
| M | Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test with $t_m = 10$ s, Partial Discharge < 5 pC | 904 ⁹⁰⁴ | V _{peak} | |
| V _{PR} | Input-to-Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with t _m = 1 s, Partial Discharge < 5 pC | 1060 | V _{peak} | |
| VIORM | Maximum Working Insulation Voltage | 565 | V _{peak} | |
| V _{IOTM} | Highest Allowable Over-Voltage | 4000 | V _{peak} | |
| | External Creepage | ≥ 4 | mm | |
| | External Clearance | ≥ 4 | mm | |
| DTI | Distance Through Insulation (Insulation Thickness) | ≥ 0.4 | mm | |
| Τ _S | Case Temperature ⁽¹⁾ | 150 | °C | |
| I _{S,INPUT} | Input Current ⁽¹⁾ | 200 | mA | |
| S,OUTPUT | Output Power ⁽¹⁾ | 300 | mW | |
| R _{IO} | Insulation Resistance at T_S , V_{IO} = 500 V ⁽¹⁾ | > 10 ⁹ | Ω | |

Note:

1. Safety limit values - maximum values allowed in the event of a failure.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A = 25^{\circ}C$ unless otherwise specified.

| Symbol | Rating | Value | Unit |
|---------------------|--|--------------------|-------|
| TOTAL DEVI | CE | | |
| T _{STG} | Storage Temperature | -40 to +125 | °C |
| T _A | Ambient Operating Temperature | -40 to +100 | °C |
| ТJ | Junction Temperature | -40 to +125 | °C |
| T _{SOL} | Lead Solder Temperature | 260 for 10 seconds | °C |
| | Total Device Power Dissipation @ T _A = 25°C | 240 | mW |
| PD | Derate above 25°C | 2.94 | mW/°C |
| EMITTER | | | |
| I _F | Continuous Forward Current | 60 | mA |
| I _F (pk) | Forward Current – Peak (PW = 100 µs, 120 pps) | 1.0 | А |
| V _R | Reverse Voltage | 6.0 | V |
| Р | LED Power Dissipation @ $T_A = 25^{\circ}C$ | 90 | mW |
| PD | Derate above 25°C | 0.8 | mW/°C |
| DETECTOR | | | |
| Ι _C | Continuous Collector Current | 150 | mA |
| V _{CEO} | Collector-Emitter Voltage | 30 | V |
| V _{ECO} | Emitter-Collector Voltage | 7 | V |
| D | Detector Power Dissipation @ $T_A = 25^{\circ}C$ | 150 | mW |
| PD | Derate above 25°C | 1.76 | mW/°C |

Electrical Characteristics

 $T_A=25^\circ C$ unless otherwise specified.

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|----------------------|--|--|------|-------|------|------|
| EMITTER | L | | | | II | |
| | Input Forward Voltage | | | | | |
| | MOC216M, MOC217M | $I_F = 1 \text{ mA}$ | | 1.07 | 1.3 | V |
| V _F | MOC205M, MOC206M, MOC207M MOC211M, MOC212M, MOC213M | I _F = 10 mA | | 1.15 | 1.5 | V |
| I _R | Reverse Leakage Current | V _R = 6 V | | 0.001 | 100 | μA |
| C _{IN} | Input Capacitance | | | 18 | | pF |
| DETECTO | DR | | | | 11 | |
| I _{CEO1} | | $V_{CE} = 10 \text{ V}, \text{ T}_{A} = 25^{\circ}\text{C}$ | | 1.0 | 50 | nA |
| I _{CEO2} | Collector-Emitter Dark Current | $V_{CE} = 10 \text{ V}, \text{ T}_{A} = 100^{\circ}\text{C}$ | | 1.0 | | μA |
| | Collector-Emitter Breakdown Voltage | | | | | |
| BV _{CEO} | MOC205M, MOC206M, MOC207M | I _C = 100 μA | 70 | 100 | | V |
| DVCEO | MOC211M, MOC212M, MOC213M, MOC216M, MOC217M | I _C = 100 μA | 30 | 100 | | V |
| BV _{CBO} | Collector-Base Breakdown Voltage | I _C = 10 μA | 70 | 120 | | V |
| BV _{ECO} | Emitter-Collector Breakdown Voltage | I _E = 100 μA | 7 | 10 | | V |
| C _{CE} | Collector-Emitter Capacitance | f = 1.0 MHz, V _{CE} = 0 | | 7 | | pF |
| COUPLE | D | | | | 11 | |
| | Collector-Output Current | | | | | |
| | MOC205M | I _F = 10 mA, V _{CE} = 10 V | 40 | | 80 | % |
| | MOC206M | I _F = 10 mA, V _{CE} = 10 V | 63 | | 125 | % |
| | MOC207M | I _F = 10 mA, V _{CE} = 10 V | 100 | | 200 | % |
| CTR | MOC211M | I _F = 10 mA, V _{CE} = 10 V | 20 | | | % |
| | MOC212M | I _F = 10 mA, V _{CE} = 10 V | 50 | | | % |
| | MOC213M | I _F = 10 mA, V _{CE} = 10 V | 100 | | | % |
| | MOC216M | I _F = 1 mA, V _{CE} = 5 V | 50 | | | % |
| | MOC217M | I _F = 1 mA, V _{CE} = 5 V | 100 | | | % |
| | Collector-Emitter Saturation Voltage | | | | | |
| V _{CE(SAT)} | MOC205M, MOC206M, MOC207M MOC211M, MOC212M, MOC213M | I _C = 2 mA, I _F = 10 mA | | | 0.4 | V |
| | MOC216M, MOC217M | I _C = 100 μA, I _F = 1 mA | | | 0.4 | V |
| t _{on} | Turn-On Time | $I_{C} = 2 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_{L} = 100 \Omega$ (Figure 12) | | 7.5 | | μs |
| t _{off} | Turn-Off Time | $I_{C} = 2 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_{L} = 100 \Omega \text{ (Figure 12)}$ | | 5.7 | | μs |
| t _r | Rise Time | $I_{C} = 2 \text{ mA}, V_{CC} = 10 \text{ V}, \\ R_{L} = 100 \Omega \text{ (Figure 12)}$ | | 3.2 | | μs |
| t _f | Fall Time | $I_{C} = 2 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_{L} = 100 \Omega \text{ (Figure 12)}$ | | 4.7 | | μs |

| Symbol | Characteristic | Test Conditions | Min. | Тур. | Max. | Units |
|------------------|--------------------------------|--|------------------|------|------|--------------------|
| V _{ISO} | Input-Output Isolation Voltage | | 2500 | | | VAC _{RMS} |
| C _{ISO} | Isolation Capacitance | V _{I-O} = 0 V, f = 1 MHz | | 0.2 | | pF |
| R _{ISO} | Isolation Resistance | V _{I-O} = ±500 VDC, T _A = 25°C | 10 ¹¹ | | | Ω |
| | | | | | | |
| | | | | | | |
| | | | | | | |



$I_{\rm C}$ – OUTPUT COLLECTOR CURRENT (NORMALIZED) T_A = −55°C 1.3 $T_A = 25^{\circ}C$ 1.2 0.1 = 100° 1.1 1.0 100 10 IF - LED FORWARD CURRENT (mA) 0.01 Figure 3. LED Forward Voltage vs. Forward Current 0.1 10 IC - OUTPUT COLLECTOR CURRENT (NORMALIZED) 1.6 - OUTPUT COLLECTOR CURRENT (NORMALIZED) 1.4 1.2 1.0 0.8 0.6 0.4 0.2 NORMALIZED TO TA = 25°C _0 0.1 0.0 -80 -60 -40 -20 0 20 40 60 80 100 120 0 2 з T_A – AMBIENT TEMPERATURE (°C) Figure 5. Output Current vs. Ambient Temperature 10000 1.0 - COLLECTOR -EMITTER DARK CURRENT (nA) 0.9 V_{CE} = 10 V 1000 $I_F = 20 \text{ mA}$ 0.8 0.7 100 0.6 NORMALIZED CTR 0.5 10 0.4 0.3 0.2 CEO 0.1 0.0 0.1 10 20 40 60 80 100 T_A – AMBIENT TEMPERATURE (°C) Figure 7. Dark Current vs. Ambient Temperature ©2005 Fairchild Semiconductor Corporation MOC20xM, MOC21xM Rev. 1.0.3 6

Typical Performance Curves

1.8

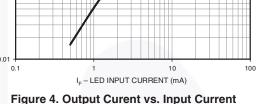
1.7 1.6

1.5

1.4

- FORWARD VOLTAGE (V)

2



10

1

V_{CE} = 5 V NORMALIZED TO I_F = 10 mA

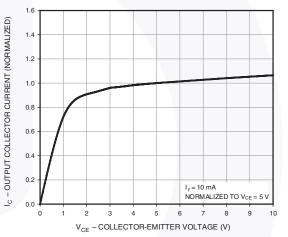
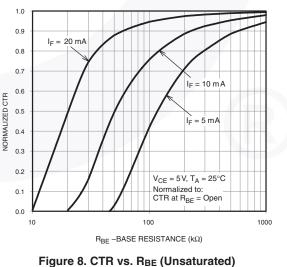
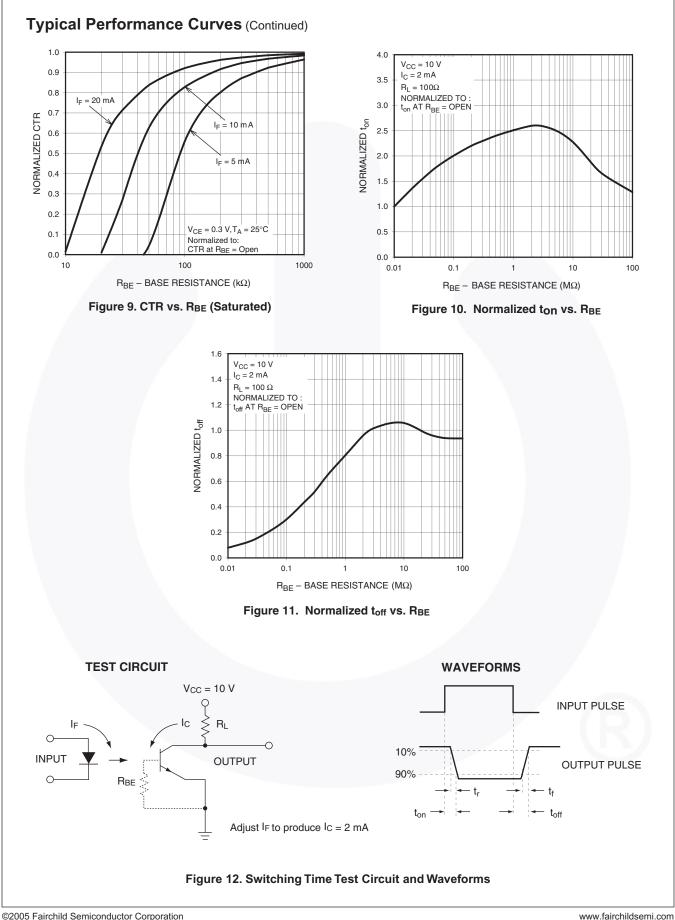


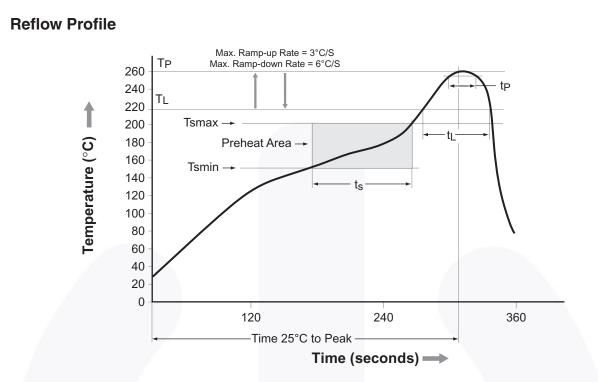
Figure 6. Output Current vs. Collector-Emitter Voltage



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MOC20xM, MOC21xM — 8-pin SOIC Single-Channel Phototransistor Output Optocoupler



| Profile Freature | Pb-Free Assembly Profile | |
|--|--------------------------|--|
| Temperature Minimum (Tsmin) | 150°C | |
| Temperature Maximum (Tsmax) | 200°C | |
| Time (t _S) from (Tsmin to Tsmax) | 60–120 seconds | |
| Ramp-up Rate (t _L to t _P) | 3°C/second maximum | |
| Liquidous Temperature (T _L) | 217°C | |
| Time (t_L) Maintained Above (T_L) | 60–150 seconds | |
| Peak Body Package Temperature | 260°C +0°C / –5°C | |
| Time (t _P) within 5°C of 260°C | 30 seconds | |
| Ramp-down Rate $(T_P \text{ to } T_L)$ | 6°C/second maximum | |
| Time 25°C to Peak Temperature | 8 minutes maximum | |

Ordering Information

| Part Number | Package | Packing Method |
|-------------|---|----------------------------|
| MOC205M | Small Outline 8-Pin | Tube (100 Units) |
| MOC205R2M | Small Outline 8-Pin | Tape and Reel (1000 Units) |
| MOC205VM | Small Outline 8-Pin, DIN EN/IEC60747-5-5 Option | Tube (100 Units) |
| MOC205R2VM | Small Outline 8-Pin, DIN EN/IEC60747-5-5 Option | Tape and Reel (1000 Units) |

Note:

2. The product orderable part number system listed in this table also applies to the MOC20XM and MOC21XM products.

Marking Information

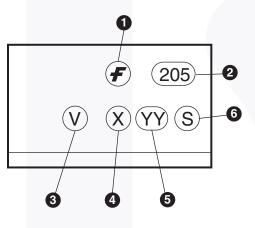
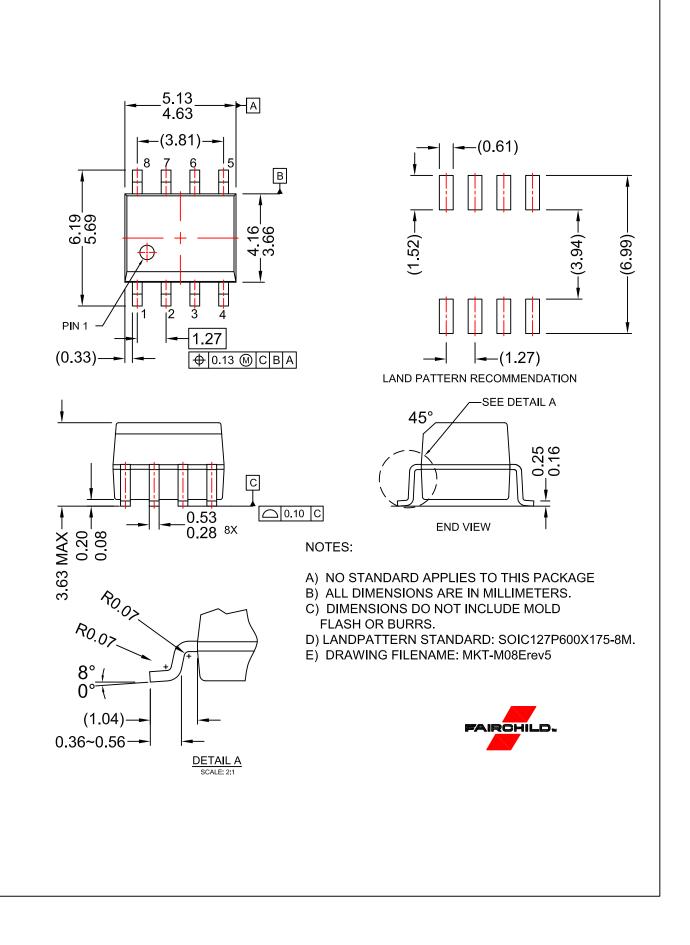


Figure 14. Top MarkTop Mark

Table 1. Top Mark Definitions

| 1 | Fairchild Logo |
|---|---|
| 2 | Device Number |
| 3 | DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option) |
| 4 | One-Digit Year Code, e.g., "4" |
| 5 | Digit Work Week, Ranging from "01" to "53" |
| 6 | Assembly Package Code |



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